# 2SC3932

### Silicon NPN epitaxial planar type

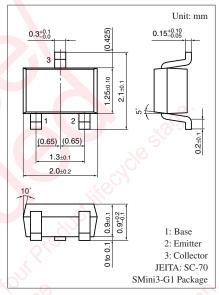
For high-frequency amplification/oscillation/mixing

#### ■ Features

- High transition frequency f<sub>T</sub>
- S-Mini type package, allowing downsizing of the equipment and automatic insertion through the tape packing

### ■ Absolute Maximum Ratings $T_a = 25^{\circ}C$

Parameter	Symbol	Rating	Unit	
Collector-base voltage (Emitter open)	$V_{CBO}$	30	V	
Collector-emitter voltage (Base open)	$V_{CEO}$	20	V	
Emitter-base voltage (Collector open)	V <sub>EBO</sub>	3	V	
Collector current	$I_{C}$	50	mA	
Collector power dissipation	$P_{C}$	150	mW	
Junction temperature	T <sub>j</sub>	150	°C	
Storage temperature	T <sub>stg</sub>	-55 to +150	°C	



Marking Symbol: R

## ■ Electrical Characteristics $T_a = 25$ °C $\pm 3$ °C

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	V <sub>CBO</sub>	$I_C = 100 \mu\text{A},  I_E = 0$	30			V
Emitter-base voltage (Collector open)	$V_{EBO}$	$I_E = 10 \mu\text{A},  I_C = 0$	3			V
Base-emitter voltage	$V_{BE}$	$V_{CB} = 10 \text{ V}, I_E = -2 \text{ mA}$	1.90	720		mV
Forward current transfer ratio	h <sub>FE</sub>	$V_{CB} = 10 \text{ V}, I_E = -2 \text{ mA}$	25		250	_
Transition frequency *	$f_T$	$V_{CB} = 10 \text{ V}, I_E = -15 \text{ mA}, f = 200 \text{ MHz}$	800		1600	MHz
Reverse transfer capacitance (Common base)	C <sub>rb</sub>	$V_{CE} = 6 \text{ V}, I_C = 0, f = 1 \text{ MHz}$		0.8		pF
Reverse transfer capacitance (Common emitter)	C <sub>re</sub>	$V_{CB} = 10 \text{ V}, I_E = -1 \text{ mA}, f = 10.7 \text{ MHz}$		1.0	1.5	pF
Power gain	$G_{P}$	$V_{CB} = 10 \text{ V}, I_{E} = -1 \text{ mA}, f = 200 \text{ MHz}$		20		dB

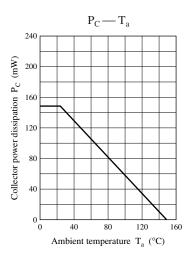
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

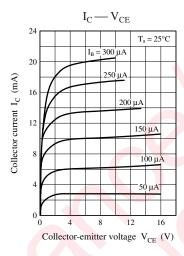
#### 2. \*: Rank classification

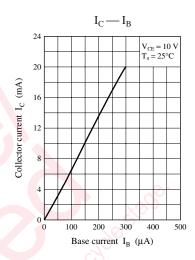
Rank	Т	S	No-rank
$f_T$	800 to 1400	1000 to 1600	800 to 1600
Marking symbol	RT	RS	R

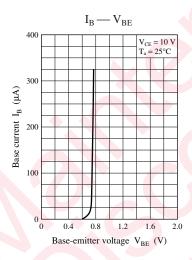
Product of no-rank is not classified and have no indication for rank.

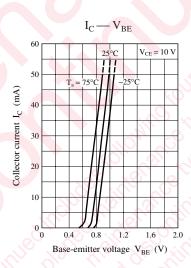
### **Panasonic**

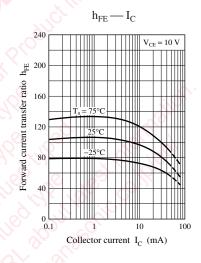


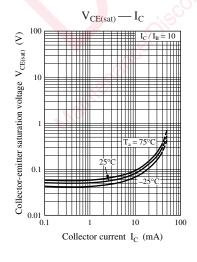


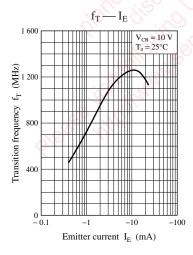


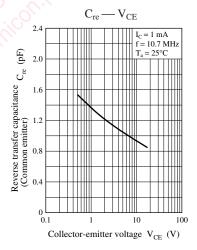






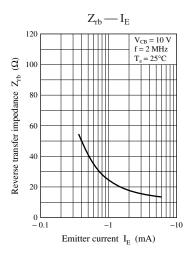


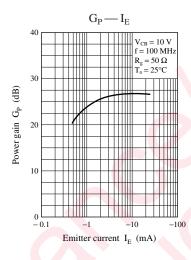


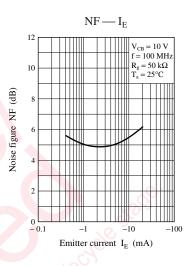


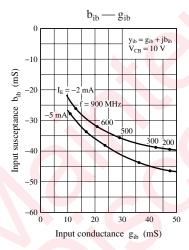
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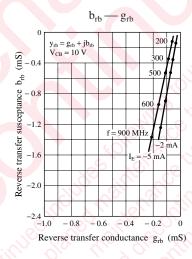
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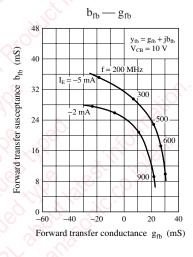


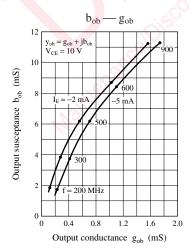












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